

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
30 March 2006 (30.03.2006)

PCT

(10) International Publication Number
WO 2006/033872 A2

(51) International Patent Classification:
H01L 21/302 (2006.01)

(74) Agent: **BROOKS, Kenneth C.**; P.O. Box 81536, Austin,
Texas 78708-1536 (US).

(21) International Application Number:
PCT/US2005/032276

(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(22) International Filing Date:
12 September 2005 (12.09.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/946,577 21 September 2004 (21.09.2004) US
10/946,574 21 September 2004 (21.09.2004) US
10/946,566 21 September 2004 (21.09.2004) US
10/946,159 21 September 2004 (21.09.2004) US
10/946,565 21 September 2004 (21.09.2004) US

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

(71) Applicant (*for all designated States except US*): **MOLECULAR IMPRINTS, INC.** [US/US]; 1807 West Braker Ln, Bldg. C-100, Austin, Texas 78758-3605 (US).

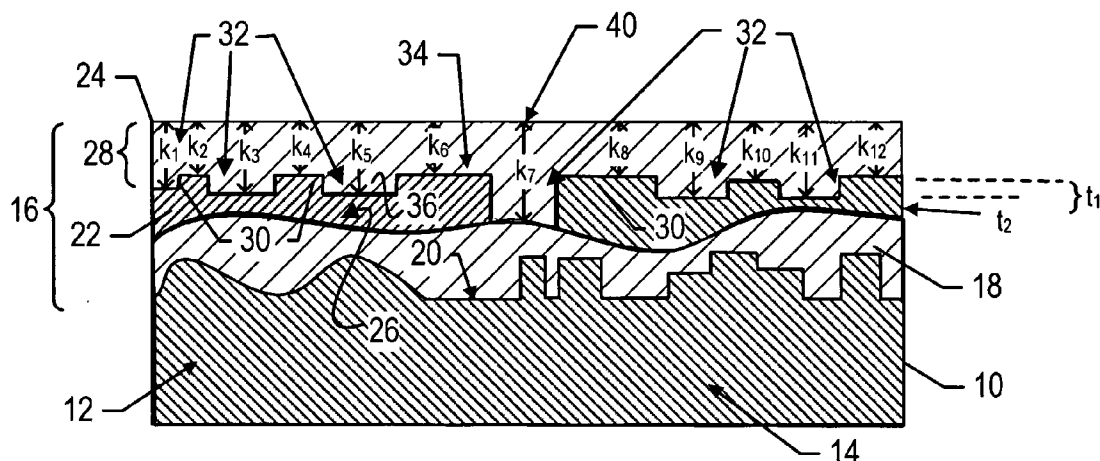
Published:

— without international search report and to be republished upon receipt of that report

(72) Inventors: **SREENIVASAN, Sidigata V.**; 10502 Grand Oak Drive, Austin, Texas 78750 (US). **MILLER, Michael N.**; 11601 Broad Oaks Drive, Austin, Texas 78759 (US). **STACEY, Nicholas A.**; 3209 Bonnie Road, Austin, Texas 78703 (US). **WANG, David C.**; 11209 Gorham Glen Court, Austin, Texas 78739 (US).

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: METHOD OF FORMING AN IN-SITU RECESSED STRUCTURE



(57) Abstract: The present invention features a method of patterning a substrate that includes forming, on the substrate, a multi-layer film with a surface, an etch rate interface and an etch-differential interface. The etch-differential interface is defined between the etch rate interface and the surface. A recorded pattern is transferred onto the substrate defined, in part, by the etch-differential interface. The recorded pattern has etched pattern characteristics (EPC) that define the shape of the pattern formed for a given etch process or set of etch processes. The etch-differential interface modifies the EPC. By establishing a suitable etch-differential interface, one may obtain a recorded pattern that differs substantially in shape compared with the shape of the patterned layer or the same pattern may be obtained.

WO 2006/033872 A2